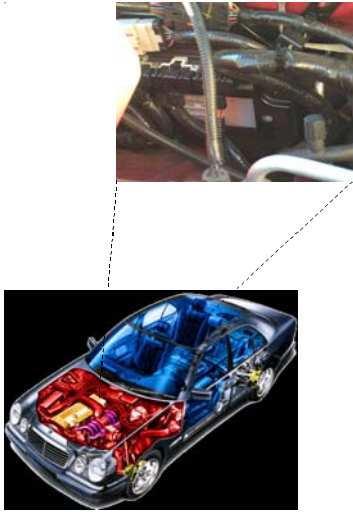


IMAPS International Conference and Exhibition on *High Temperature Electronics* (HiTEC 2008)

May 12-15, 2008
Hotel Albuquerque Old Town
Albuquerque, New Mexico, USA



General Chair:

R. Wayne Johnson, Auburn University
johnson@eng.auburn.edu

General Co-Chair:

Randy Normann, Sandia National Laboratories
ranorma@sandia.gov

Technical Chair:

Patrick McCluskey, University of Maryland
mcclupa@eng.umd.edu

Technical Co-Chair:

Susan Heidger, Air Force Research Laboratory
susan.heidger@us.af.mil

Produced by:

International Microelectronics And
Packaging Society (IMAPS)
*Bringing Together The Entire
Microelectronics Supply Chain!*



PROGRAM OVERVIEW

Plenary Session I

Chair: Patrick McCluskey, University of Maryland

Session TA1: SOI Devices I

Chair: Bruce Ohme, Honeywell International

Session TA2: Packaging I

Chair: David Shaddock, General Electric Research

Session TP1a: SOI Devices II

Chair: Randy Normann, Sandia National Laboratories

Session TP2a: Capacitors I

Chair: Mike Lanagan, Pennsylvania State University

Session TP1b: SIC Devices

Chair: Jeff Casady, SemiSouth Laboratories

Session TP2b: Capacitors II

Chair: John Witham, Sandia National Laboratories

Plenary Session II

Chair: R. Wayne Johnson, Auburn University

Session WA1: Memory/Microprocessors

Chair: Chris Hutchens, Oklahoma State University

Session WA2: Packaging II

Chair: Laura Marlino, Oak Ridge National Laboratory

Session WP1a: Devices

Chair: Bruce Geil, US Army Research Laboratory

Session WP2a: Packaging III

Chair: Harold Snyder, Physical Solutions

Session WP1b: High Temperature Batteries

Chair: David Ryan, Air Force Research Laboratory

Session WP2b: Packaging IV

Chair: Milton Watts, Quartzdyne Electronics

Plenary Session III

Chair: Susan Heidger, Air Force Research Laboratory

Session THA1: Sensors

Chair: Liang-Yu Chen, OAI/NASA Glenn Research Center

Session THA2: Packaging (Substrates)

Chair: Colin Johnston, Faraday Advance - Materials KTN



Message from the General Chair:

The members of the Conference Committee are pleased to invite you to the IMAPS High Temperature Electronics Conference (HiTEC 2008).

This is the premier event addressing the needs of the high temperature electronics community. Applications for high temperature electronics include underhood automotive, oil well logging, geothermal, more electric aircraft, space, industrial sensors, etc.

HiTEC 2008 provides a comprehensive technical program addressing the applications and the latest developments in devices, circuits, MEMS, sensors, packaging, power sources, and materials to address the challenges of these applications.

Tabletop exhibits will complement the technical program by providing you an opportunity to view the latest products for high temperature electronics.

This is a truly unique opportunity for suppliers, fabricators, and users to meet and talk about the needs, issues and opportunities in this exciting and important area.

Please join us in wonderful Albuquerque, New Mexico, for HiTEC 2008

R. Wayne Johnson, Auburn University



HiTEC Tabletop Exhibition

"An opportunity to talk to industry leaders"

Exhibit Hours

Tuesday - May 13 12:00 noon - 7:30 pm
Refreshment Breaks, Lunch and a Reception will be held in the Exhibit Hall.

Wednesday - May 14 10:00 am - 3:00 pm
Refreshment Breaks and Lunch will be held in the Exhibit Hall.

Tabletop Registration Fees

	On/Before 4/11/08	After 4/11/08
IMAPS Corporate Member	\$575	\$675
Non-Corporate Member	\$675	\$775

Included with your registration: one six-foot draped table, two chairs, carpeting, one copy of Proceedings on CD-ROM, one copy of the final list of attendees and exhibit hall admission for two booth personnel.

Only tabletop exhibits will be accepted. Free standing exhibits will not be allowed at this event.

For more information, visit www.imaps.org/hitec or contact Ann Bell at 202-548-8717

Exhibitors on HiTEC 2008 CD-ROM

IMAPS will provide all exhibitors an opportunity to provide an unlimited amount of pages of company products, services and contact information to be included on the Proceedings CD-ROM. These CD-ROMs are provided to all technical conference attendees and are for sale through IMAPS to all industry professionals. This unique feature will allow exhibiting companies an unlimited amount of promotional material for their products and services that will go well beyond their exposure at the Conference.

There is no charge for this optional feature. **However, the deadline (4/11/08) must be met in order to be included.** Submissions must be sent electronically in one (1) file, either PDF or Word, that is easy to open, not password-protected and in a logical format. Any materials not sent in the required format or that arrive after the deadline, may not appear on the CD-ROM. **Send files to Ann Bell abell@imaps.org on or before April 11, 2008.**

Monday, May 12

REGISTRATION: 4:00 PM – 6:30 PM

OPENING RECEPTION: 6:30 PM – 8:00 PM

Tuesday, May 13

REGISTRATION: 7:00 AM – 7:30 PM

CONTINENTAL BREAKFAST: 7:00 AM – 7:45 AM

EXHIBIT HOURS: 12:00 NOON – 7:30 PM

REFRESHMENT BREAKS, LUNCH AND RECEPTION IN THE EXHIBIT HALL

RECEPTION IN THE EXHIBIT HALL: 6:00 PM – 7:30 PM

OPENING REMARKS: 7:45 AM – 8:00 AM

CONFERENCE CHAIRS

PLENARY SESSION I

Chair: Patrick McCluskey, University of Maryland

8:00 am – 10:00 am

High Temperature Electronics - A European Perspective
Colin Johnston, Faraday Advance - Materials KTN Oxford

Progress in High Temperature Power Electronics for the More Electric Aircraft
Joseph Weimer, U.S. Air Force

High Temperature Electronics for Future CAR
Laura Marilino, Oak Ridge National Laboratory

BREAK IN FOYER: 10:00 AM – 10:30AM

TA1 - SOI DEVICES I

Chair: Bruce Ohme, Honeywell International
10:30 am – 12:00 noon

SOI Based Integrated Circuits for High Temperature Applications
M.A. Huque (University of Tennessee), B.J. Blalock, C. Su, R. Vijayaraghavan, S.K. Islam, L.M. Tolbert

Study of Circular Gate Devices SOI nMOSFET at High Temperatures
Luciano Mendes Almeida (Centro Universitario da FEI Brazil), Marcello Bellodi

Analysis of Annular MOSFET Leakage at High Temperature
Sheshnag Rangaraj (Oklahoma State University), Chris Hutchens

TA2 - PACKAGING I

Chair: David Shaddock, General Electric Research
10:30 am – 12:00 noon

High Temperature and High Heat Flux Thermal Management for Electronics
William G. Anderson (Advanced Cooling Technologies, Inc.), David B. Sarraf, Scott D. Garner

Effect of Bonding Temperature, Post-Bond Heat Treatment and Extended Range Thermal Cycling on the Reliability of Al Wire Bonds
Loh Wei Sun (The University of Sheffield), S.C. Hogg, R.J. Ikujeniya, M.R. Corffield, P. Agyakwa, C.M. Johnson

Integrated Microheater for Accelerated Thermal Cycling of Microelectronics Ball Bonds
Michael Mayer, University of Waterloo Canada

Conference Proceedings

Conference Hotel

If you are unable to attend the Conference and would like a copy of the CD-ROM Proceedings, you may purchase a copy by using the registration form. Your copy will be mailed to you after the event.

The cost is \$200 for members; \$300 for non-members,* plus shipping and handling. Reserve your copy on-line at www.imaps.org/hitec or call Rick Mohn at 202-548-8703.

*includes 1 year IMAPS individual membership.

HOTEL ALBUQUERQUE OLD TOWN
800 RIO GRANDE BLVD. NW
ALBUQUERQUE, NM 87104

PHONE: 505-843-6300 OR 800-237-2133

Single/Double \$159

Please reference IMAPS when making reservation to receive the group rate.

LUNCH BREAK IN THE EXHIBIT HALL: 12:00 NOON – 1:30 PM
LUNCH SERVED AT 12:30

TP1A - SOI DEVICES II

Chair: Randy Normann, Sandia National Laboratories
1:30 pm – 3:00 pm

Junction Temperature Measurement and Thermal Control of a DC/DC Converter for High Temperature Applications
Andreas Koenig (RWTH Aachen University, ISEA), Thomas Plum, Peter Fidler, Rik De Doncker

Extreme Temperature Switch Mode Power Supply based on Vee-square Control Using SiC, Si on Sapphire, Hybrid Technology

Vijayaraghavan Madhuravasal (Oklahoma State University), Srinivasan Venkataraman, Chia-Ming Liu, Chris Hutchens

A High Temperature (225 C+) Silicon-On-Insulator (SOI) Gate Driver IC for Silicon Carbide (SiC) JFET

Edgar Cilio (APEI), Jared Hornberger, Robert Schubach, Alexander Lostetter, Allan Mantooth

TP2A - CAPACITORS I

Chair: Mike Lanagan, Pennsylvania State University
1:30 pm – 3:00 pm

High Temperature Glass-based Dielectrics for Capacitors
Michael Lanagan (Penn State University), Badri Rangarajan, Steve Perini, Carlo Pantano, Samuel Corzone

Current-Voltage Testing of Candidate Dielectric Materials for 500 C SiC Integrated Circuits

Carl W. Chang (ASRC Aerospace and NASA Glenn Research Center), Philip G. Neudeck, Glenn M. Beheim, David J. Spry

Fabrication and Characterization of Wound Capacitors using Amorphous Silicon Dioxide as the Dielectric Material

Keith D. Jamison (Nanohmics, Inc.), R.D. Wood, B.G. Zollars, M.E. Kordesch, M. Carter

BREAK IN THE EXHIBIT HALL: 3:00 PM – 3:45 PM

TP1B - SiC DEVICES

Chair: Jeff Casady, SemiSouth Laboratories
3:45 pm – 5:45 pm

6H-SiC Transistor Integrated Circuits Demonstrating Prolonged Operation at 500C

Philip G. Neudeck (NASA-Glenn Research Center), David J. Spry, Liangy Chen, Carl W. Chang, Glenn M. Beheim, Robert S. Okojie, Laura J. Evans, Roger Meredith, Terry Ferrier, Michael J. Krasowski, Norman F. Prokop

High Temperature DC and Switching Performance of 20A 800V Normally-off SiC VJFET

I. Sankin (SemiSouth Laboratories, Inc.), N. Merrett, W. King, V. Bondarenko, A. Ritenour, R. Kelly, W. Draper, D. Sheridan

Reliable Silicon Carbide MOSFET Operation at 300C Junction Temperature

Jim Richmond (Cree, Inc.), Brett Hull, Sei-Hyung Ryu, Anant Agarwal, John Palmour, Jim Scofield

300 C Silicon Carbide JFET Technology for Power Conditioning

Victor Veliadis (Northrop Grumman), Harold Hearne, Megan McCoy, Ty McNutt, Paul Potyraj

TP2A - CAPACITORS II

Chair: John Witham, Sandia National Laboratories
3:45 pm – 5:45 pm

High Dielectric Constant Capacitors for High Temperature Power Inverters in Hybrid Vehicles

U. Balachandran (Argonne National Laboratories), B. Ma, D.K.Kwon, M. Narayanan

High Temperature and High Pressure Performance of Ceramic Chip Capacitors-Study of Leakage Current

Rolf Johannessen (SINTEF ICT, Norway), Froydis Oldervoll, Frode Strisland, Per Ohlckers

Defect Leakage Current Noise in Multilayer Ceramic Capacitors - A New Reliability Sorting Procedure

Harold L. Snyder, Jr., Physical Solutions

Temperature Dependence of Electrical Breakdown in Polymer Dielectrics

Cheolhong Min (Penn State University), Michael Lanagan, Thomas Shrout

EXHIBIT HALL RECEPTION: 6:00 PM – 7:30 PM

STUDENT PAPER COMPETITION SPONSORED BY:



Wednesday, May 14

REGISTRATION: 7:00 AM – 5:00 PM

CONTINENTAL BREAKFAST: 7:00 AM – 8:00 AM

EXHIBIT HOURS: 10:00 AM – 3:00 PM

REFRESHMENT BREAKS AND LUNCH IN THE EXHIBIT HALL

PLENARY SESSION II

Chair: R. Wayne Johnson, Auburn University
8:00 am – 10:00 am

Challenges for Power Electronics in Future Electricity Networks
C. Mark Johnson (University of Nottingham), Jon Clare, Greg Asher

A New Geothermal Plan, EGS
Randy Normann, Sandia National Laboratory

Modeling of High Temperature Device and Circuit Performance
Alan Mantooh, University of Arkansas

STUDENT PAPER COMPETITION AWARD PRESENTATION

FOLLOWING CONCLUSION OF PLENARY II

BREAK IN THE EXHIBIT HALL: 10:00 AM – 10:30 AM

WA1 - MEMORY / MICROPROCESSORS

Chair: Chris Hutchens, Oklahoma State University
10:30 am – 12:00 noon

General Purpose 256 Kbit Non-Volatile Memory for Operation to 250C
Bruce Ohme, Honeywell International

Microcontroller with Memory for Extreme Temperature Applications
R. Sridharan (Oklahoma State University), H.M. Soo, C. Hutchens, C.M. Liu, Z. Yuan, S. Velore, J. Gaisler, M. Willet, V. Madhuravasal

Single Package Re-configurable Processor for Data Acquisition at 250C
Thomas Romanko (Honeywell International), Michael Johnson, Bruce Ohme

WA2 - PACKAGING II

Chair: Laura Marlino, Oak Ridge National Laboratory
10:30 am – 12:00 noon

Packaging Technology for High Temperature SiC Capacitive Pressure Sensors
Liangyu Chen (OAI / NASA-Glenn Research Center), Glenn M. Beheim, Laura Evans, Roger D. Meredith, Jeff Melzak

High Temperature, High Power SiC Module Design: Packaging Architecture and Material Consideration
John Shen (University of Central Florida), Brian Grummel, Ryan McClure, Ali Gordon, Allen Hefner

High Temperature Planar Package with Sintered Nanosilver Paste Interconnects
Naili Yue (Virginia Tech), Ying Lu, Jesus N. Calata, Thomas G. Lei, Guo-Quan Lu, Khai Ngo

LUNCH IN THE EXHIBIT HALL: 12:00 NOON – 1:00 PM

HiTEC Speaker Information

Final Manuscripts for the HiTEC Proceedings are due April 4, 2008.

Send Your Final Manuscript Via E-Mail to jmorris@imaps.org, in PDF format only (PDF can be in color).

PowerPoint/Presentation file used during session: Speaker's responsibility to bring to session on USB and/or CD (recommended to have back-up on personal laptop, cd-rom, or memory stick). Laptops will be provided by IMAPS in each session room.

Selected Manuscripts from HiTEC will be considered for publishing in the *Journal of Microelectronics and Electronic Packaging*. Invitations will be made separately. Inquiries can be sent to jmep@imaps.org.

Speakers must register for this conference at the reduced speaker rates. Early registration deadline and hotel cut-off is April 11, 2008. Hotel availability and pricing will not be guaranteed after April 11.

WP1A - DEVICES

Chair: Bruce Geil, US Army Research Laboratory
1:00 pm – 2:30 pm

Temperature Tolerance Characteristics of the Nanodiamond Lateral Vacuum Field Emission Device
J.L. Davidson (Vanderbilt University), K. Subramanian, W.P. Kang, R. Schroeder

Thermally-Adjustable Resistors for Fine-Tuning High-Temperature Electronics Circuits
Les M. Landsberger (Microbridge Technologies Canada, Inc.), Rick Williston, Bowei Zhang, Oleg Grudin, Gennadiy Frolov, Tommy Tsang

Characterization of Power MOSFET Bipolar Switches at High Temperature
Steven A. Morris, Baker Hughes/INTEQ

WP2A - PACKAGING III

Chair: Harold Snyder, Physical Solutions
1:00 pm – 2:30 pm

Low Temperature Sintering of a Nanoscale Silver-Gold Paste for High Temperature Chip Attachment
Jesus N. Calata (Virginia Tech), Guo-quan Lu, Thomas Ge. Lei, Mary Gail Koebke, Bruce Geil

High Temperature Die Attach
Pedro O. Quintero (University of Maryland, College Park), Timothy Oberc, F. Patrick McCluskey

Die Attach for High Temperature Electronics Packaging
R. Wayne Johnson (Auburn University), Ping Zheng, Albrez Wiggins

BREAK IN THE EXHIBIT HALL: 2:30 PM – 3:00 PM

WP1B - HIGH TEMPERATURE BATTERIES

Chair: David Ryan, Air Force Research Laboratory
3:00 pm – 5:30 pm

A Battery Performance Monitoring Solution in a Down-hole Environment
Paul Moody, IntelliServ

High Temperature Electrochemical Energy Storage
Scott Preston (Mobile Energy Products, Inc.), Ron Guidott, Za Johnson, Brian Burns

State of Capacity Indicator for Primary Lithium Battery Packs used in Oil Well Logging Applications
Jon Carroll (Electrochem Commercial Power), Anwar Master, Tom Skwara

Battery Performance Under Pulsed Discharge Conditions in High Temperature Applications
Arden P. Johnson (Electrochem Commercial Power), Konstantin K. Tikhonov

Altairnano Battery Performance for High Temperature Downhole Applications
Chet Sandberg, Altairnano, Inc.

WP2B - PACKAGING IV

Chair: Milton Watts, Quartzdyne Electronics
3:00 pm – 5:30 pm

Viability of an Alternative High Temperature Surface Mount Component Attach
Timothy Oberc (University of Maryland, College Park), Pedro O. Quintero, F. Patrick McCluskey

Microstructure and Mechanical Behavior of High Temperature Solders
Junghyun Cho (State University of New York at Binghamton), Harry Schoeller, Shubhra Bansal, Aaron Knobloch, David Shaddock

High Temperature Electronics Packaging based on Polyimide Flex
David Shaddock (General Electric Research), Aaron J. Knobloch, Shubhra Bansal, Chris Kapusta, Harry Schoeller, Junghyun Cho

Assessment of the Reliability of High Temperature Electronics Packaging Technology
David Shaddock (GE Aviation Systems, UK), Colin Johnston, Jim Gulliver, Mark Langley, Robin Pittson, Mike Firmstone

Rapid Thermal Processed Attachment Materials
Adam McClure (University of Maryland, College Park), Pedro Quintero, Patrick McCluskey, Bruce Geil

Thursday, May 15

REGISTRATION: 7:00 AM – 12:20 PM

CONTINENTAL BREAKFAST: 7:00 AM – 8:00 AM

PLENARY SESSION III

Chair: Susan Heidger, Air Force Research Laboratory
8:00 am – 10:00 am

Design Considerations for High Temperature Hybrid Manufacturability
Milton Watts, Quartzdyne Electronics

Reliability Assessment of High Temperature Electronics and Packaging Technologies for NASA Missions
Yuan Chen (Jet Propulsion Laboratory), Linda Del Castillo, Nazeeh Aranki, Chris Assad, Mike Mazzola, Mohammad Mojarradi, Elizabeth Kolawa

Army High Temperature Electronics Activities and Needs
Bruce Geil, Army Research Laboratory

BREAK IN THE FOYER: 10:00 AM – 10:20 AM

THA1 - SENSORS

Chair: Liang-Yu Chen, OAI/NASA Glenn Research Center
10:20 am – 12:20 pm

Development of a Temperature Sensor for Jet Engine and Space Mission Applications
Dennis Culley (NASA-Glenn Research Center), Richard L. Patterson, Ahmad Hammoud, Malik Elbuluk

SiC MEMS Capacitive Pressure Sensor for High Temperature Applications
Jeffrey M. Melzak (FLX Micro, Inc.), Glenn M. Beheim, Laura Evans, Roger D. Meredith, Lianyu Chen

A Battery-less Transponder for Extreme Environment Telesensing and RFID
Greg Horler (Instrumentel Ltd., Leeds University), D. McGorman, N. Curry, J. Birch

High Temperature Piezoelectric Single Crystal ReCa4O (BO3)3 for Sensor Applications
Shujun Zhang (Penn State University), Thomas R. Shrout, Yiting Fei, Bruce H.T. Chai

THA2 - PACKAGING (SUBSTRATES)

Chair: Colin Johnston, Faraday Advance - Materials KTN
10:20 am – 11:50 am

Stress Management in a High Temperature Multilayered Composite Structure
Douglas C. Hopkins (University of Buffalo), David W. Kellerman, Kevin Enser

Dielectric Performance of Sapphire at High Temperatures
Liangyu Chen, OAI / NASA-Glenn Research Center

Large Area Single Crystal Diamond Wafers for High Temperature Electronics
Patrick Doering (Apollo Diamond), Josh Tower, Alfred Genis, Robert Linares

CLOSING REMARKS FOLLOWED BY ORGANIZERS MEETING: 12:30 NOON – 2:00 PM

THANK YOU

A SPECIAL *THANK YOU*

TO ALL OF THE MEMBERS OF THE ORGANIZING COMMITTEE,
THE LOCAL VOLUNTEERS, AND THE SESSION CHAIRS
WHO WILL MAKE HITEC 2008 A GREAT SUCCESS!

Upcoming Events ...

Global Business Council (GBC) Spring Conference

Radisson Fort McDowell Resort and Casino
Scottsdale/Fountain Hills, Arizona - USA

March 16 - 17, 2008

www.imaps.org/gbc

Co-located with Device Packaging Conference and Exhibition

International Conference and Exhibition on Device Packaging

Radisson Fort McDowell Resort and Casino
Scottsdale/Fountain Hills, Arizona - USA

March 17 - 20, 2008

www.imaps.org/devicepackaging

Co-located with the GBC Spring Conference

IMAPS/ACerS 4th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT)

Holiday Inn - City Centre
Munich, Germany

April 21 - 24, 2008

www.cicmt.org

Topical Workshop and Tabletop Exhibition on Military, Aerospace, Space and Homeland Security (MASH): Packaging Issues and Applications

The Conference Center at the Maritime Institute
Linthicum Heights (Baltimore), Maryland - USA

April 28 - 30, 2008

www.imaps.org/mash

Co-located with the ATW on Advanced Substrates

ATW and Tabletop Exhibition on Advanced Substrates and Next Generation Semiconductors

The Conference Center at the Maritime Institute
Linthicum Heights (Baltimore), Maryland - USA

April 30 - May 1, 2008

www.imaps.org/substrates

Co-located with the MASH Workshop

41st International Symposium on Microelectronics (IMAPS 2008)

Rhode Island Convention Center
Providence, Rhode Island - USA

November 2 - 6, 2008

www.imaps2008.org

REGISTRATION FORM

REGISTER ON-LINE AT WWW.IMAPS.ORG/HITEC

HITEC 2008 CONFERENCE - MAY 12 - 15, 2008

Dr. Mr. Ms.

Member ID# _____

First Name _____ M.I. _____ Last Name _____

Company/Affiliation _____ Job Position _____

Address _____

City _____ State _____ Zip _____ Country _____

Phone _____ Fax _____ E-mail _____

REGISTRATION FEES: EARLY REGISTRATION ENDS 4/11/08

CONFERENCE FEES

(On or before 4/11) (After 4/11)

- | | | |
|--|-------|-------|
| <input type="checkbox"/> IMAPS Member | \$500 | \$600 |
| <input type="checkbox"/> Non-member | \$600 | \$700 |
| <input type="checkbox"/> Speaker <input type="checkbox"/> Chair <input type="checkbox"/> Chapter Officer | \$375 | \$475 |
| <input type="checkbox"/> Student | \$200 | \$300 |

All conference fees above include access to all sessions and exhibits events, an extended abstract book, all meals listed and a Proceedings on CD-Rom. Each registration above also includes a one-year individual membership or a one-year individual membership renewal in IMAPS. Corporate and affiliate memberships do not apply.

- | | | |
|--|------|------|
| <input type="checkbox"/> Exhibits Only | \$25 | \$25 |
|--|------|------|

TABLETOP EXHIBIT (MAY 13TH & 14TH)

- | | | |
|--|-------|-------|
| <input type="checkbox"/> IMAPS Corporate Member | \$575 | \$675 |
| <input type="checkbox"/> Non-IMAPS Corporate Members | \$675 | \$775 |
| <input type="checkbox"/> Yes, we will participate in the CD-ROM* | | |

*see inside front cover for details and deadlines.

ADDITIONAL PURCHASES

- | | | |
|---|-------|-------|
| <input type="checkbox"/> Guest/Family Member (meals only) | \$160 | \$160 |
| <input type="checkbox"/> CD-ROM Proceedings (Member Rate) | \$200 | \$200 |
| <input type="checkbox"/> CD-ROM Proceedings (Non-Member Rate) | \$300 | \$300 |
| <input type="checkbox"/> Add to Ship in the US | \$7 | \$7 |
| <input type="checkbox"/> Add to Ship Overseas | \$25 | \$25 |

HOUSING (Hotel Cut-off is April 11, 2008)

Housing Accommodations must be made directly to:

Hotel Albuquerque Old Town
800 Rio Grande Blvd. NW
Albuquerque, NM 87104
Phone: 505-843-6300 or 800-237-2133

Single/Double - \$159

Please reference IMAPS when making reservation to receive the group rate.

PAYMENT

HITEC08

Conference Fee: \$ _____

Tabletop Exhibit Fee: \$ _____

Additional Purchases: \$ _____

Total Payment Due: \$ _____

Enclosed is a check payable in US funds to IMAPS

Charge my fees to:

Visa MasterCard Discover Amex Diners Club

Card# _____ Exp. _____

Signature _____

Card billing address, if different from above: (required)

For Wire Transfer information, call 202-548-8703.

Mail this form with payment to: IMAPS * 611 2nd Street, NE * Washington, DC 20002-4909. For credit card transactions, register on-line: www.imaps.org; or register by phone with your credit card by calling 202-548-4001; Fax: 202-548-6115. Additional information? E-mail: IMAPS@imaps.org, or visit our web site: <http://www.imaps.org>. Cancellations will be refunded (less a \$50 processing fee) only if written notice is postmarked on or before **Friday, April 11, 2008**. No refunds will be issued after that date.

IMAPS Registration
611 2nd Street, NE
Washington, DC 20002-4909

"Address Service Requested"

Presorted
First-Class Mail
U.S. Postage
PAID
Merrifield, VA
Permit No. 6418